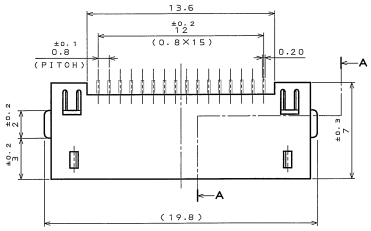
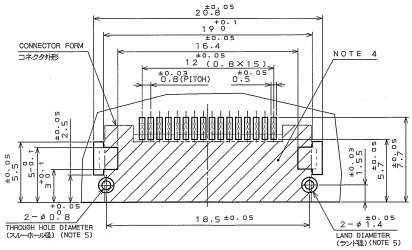
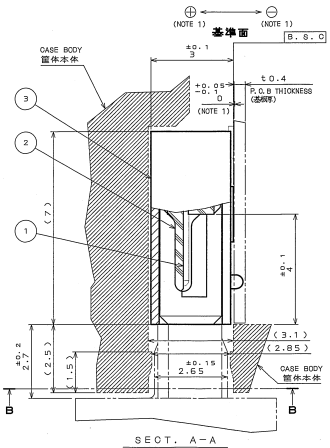
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	検図 CHK.	承認 APPD.	承認 APPD.

図面番号(DRAWING NO.) SJ101874

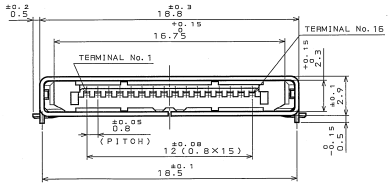


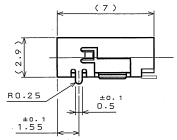


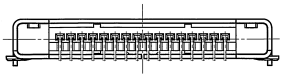
APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)

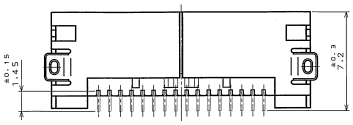


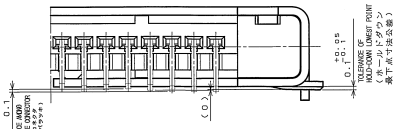
SECT. A−A
(SCALE 10:1)



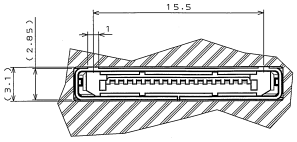








TERMINAL DIMENSION
SMT端子寸法について
(NOTE 1)



SECT. B−B

NOTE 1. THIS SHOWS THE PLUS OR MINUS DIRECTION OF SMT TOLERANCE.
THE TERMINAL DIMENSION IS $0^{+0.05}_{-0.05}$, AND THE VARIANCE WITHIN THE TOLERANCE
(THE DIFFERENCE BETWEEN MAXIMUM VALUE AND MINIMUM VALUE) SHALL BE 0.1mm MAX.
2. THE CONNECTING AREA IS PLATED WITH GOLD OVER PALLADIUM-NI OVER NICKEL.
THE TERMINAL AREA IS Au FLASH.
3. THIS SMT SHARED AREA OF THIS CONNECTOR SHELL IS NOT PLATED.
4. THE PATTERN SHOULD NOT BE LAID IN THIS SHADED AREA.
5. THE LAND SHALL BE PROVIDED AT BOTH FACES OF THE PC BOARD.
THE 0.8 DIAMETER HOLE IS THROUGH-HOLE PLATED.

注1. SMT公差部のプラス、マイナスの方向を示す。
端子寸法は$0^{+0.05}_{-0.05}$であり、公差内におけるバラツキ
(1コネクタ内のMAX値とMIN値の差)は0.1以下とする。
2. 接触部は、ニッケル上パラジウムニッケル上金メッキ
SMT部は、Auフラッシュメッキである。
3. 本コネクタシェルSMT部破断面には、メッキは施されません。
4. 本斜線部にはパターンを配線しないよう願います。
5. ランドは基板の両面に設けること。又、φ0.8の穴はスルーホールメッキであること。

NO.	DESCRIPTION	QTY.	MATERIAL	FINISH	REMARKS
3	SHELL	1	STAINLESS STEEL	GOLDEN AREA(Sn/Ni) PLATING(LEAD FREE) (NOTE 3)	
2	INSULATOR	1	PPS	—	UL94 V−0
1	CONTACT	16	COPPER ALLOY	NOTE 2	

仕様書(SPECIFICATION) JAC8−3163	原図(ORIGINAL DATE) 15.Oct.2004	尺度(SCALE) 5/1	シリーズ名(SERIES) —
一般公差(GENERAL TOLERANCE) 寸法(DIMENSION) ±0.8 / ±0.4 / ±0.1 / ±0.1 角度(ANGLES) X° ± / XX'±	製図 DR. / 設計 CHK. Y.SAITOU / 金型 APPD. — / 承認 APPD.	名称(TITLE) RL01S−R16P−SE	質量(MASS)

日本航空電子工業株式会社
JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

図面番号(DRAWING NO.) SJ101874 — 版数(REV.) 1 — SIZE A2

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